

LINEAR TECHNOLOGY MATERIALS DECLARATION

LT1461CCS8-2.5#PBF		(Engineering Calculation)		SOIC			
(printed on: 7/16/2011 12:35:19 PM)				TOTAL MASS (g):		0.07601785	
COMPONENT	VENDOR/	CONSTITUENT	CAS	CONSTITUENT	CONSTITUENT	CONSTITUENT	
MATERIAL	INDUSTRY NAMES	NAME	NUMBER	MASS (g)	(PPM) OF MATERIAL	(PPM) OF TOTAL PKG.	
Active Device	Linear Technology	Silicon (Si)	7440-21-3	0.004033	1000000	53053.33	
Die Coat	Dow Corning	Silicone	67762-90-7	0	0	0	
Lead Frame	A42	Copper (Cu)	7440-50-8	0	0	0	
		Iron (Fe)	7439-89-6	0.014071	580000	185101.3	
		Phosphorus (P)	7723-14-0	0	0	0	
		Zinc (Zn)	7440-66-6	0	0	0	
		Nickel (Ni)	7440-02-0	0.010189	420000	134034.3	
		Silicon (Si)	7440-21-3	0	0	0	
		Magnesium (Mg)	7439-95-4	0	0	0	
		Tin (Sn)	7440-31-5	0	0	0	
		Lead Frame Total:			0.02426	1000000	319135.6
Plating	PMI	Exter. Plating Pb	7439-92-1	0	0	0	
		Exter. Plating Sn	7440-31-5	0.001476852	1000000	19427.7	
		External Plating Total:			0.001476852	1000000	19427.7
		Inter. Plating Ni	7440-02-0	0	0	0	
		Inter. Plating Ag	7440-22-4	0.000194	1000000	2552.032	
		Internal Plating Total:			0.000194	1000000	2552.032
Die Attach	ELECTRICALLY CONDUCTIVE ADHESIVE	Silver (Ag)	7440-22-4	0.001116	750000	14680.76	
		Tin (Sn)	7440-31-5	0	0	0	
		Lead (Pb)	7439-92-1	0	0	0	
		Silica (SiO2)	60676-86-0	0	0	0	
		Metal Oxide		0	0	0	
		Antimony (Sb)	7440-36-0	0	0	0	
		Resin (EP)		0.000372	250000	4893.588	
Die Attach Total:			0.001488	1000000	19574.35		
Encapsulation	MULTI-AROMATIC RESIN Br/Sb FREE	Resin (EP)		0.006657	150000	87571.54	
		Bromine (Br)	40039-93-8	0	0	0	
		Silica (SiO2)	60676-86-0	0.036392	820000	478729.7	
		Antimony	1309-64-4	0	0	0	
		Trioxide (Sb2O3)					
		Metal Hydroxid		0.00111	25000	14601.83	
		Carbon Black (C)	1333-86-4	0.000222	5000	2920.367	
Encapsulation Total:			0.044381	1000000	583823.4		
Bond Wire	AFW/TANAKA/ Kn	Gold (Au)	7440-57-5	0.000185	1000000	2433.639	
Estimated							
			TOTAL MASS (g):			0.07601785	